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YOKOMIZO et al.(10) **Pub. No.: US 2022/0386467 A1**(43) **Pub. Date: Dec. 1, 2022**(54) **METHOD OF MANUFACTURING
ELECTRONIC COMPONENT****H05K 3/12** (2006.01)**H05K 3/04** (2006.01)(71) Applicant: **Murata Manufacturing Co., Ltd.**,
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(2013.01)(72) Inventors: **Satoshi YOKOMIZO**, Nagaokakyo-shi
(JP); **Shinobu CHIKUMA**,
Nagaokakyo-shi (JP); **Yohei**
MUKOBATA, Nagaokakyo-shi (JP)(21) Appl. No.: **17/752,906**(22) Filed: **May 25, 2022**(30) **Foreign Application Priority Data**

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H05K 3/34 (2006.01)(57) **ABSTRACT**

A method of manufacturing an electronic component includes applying a paste at two locations on a board main surface of a board made of alumina and applying a glass paste between the two locations, heating the board, cutting two locations where a fired layer is provided, forming a layer on an outer periphery in a vicinity of a board end surface, forming a plated layer on an outer periphery of the layer, forming a second plated layer on an outer periphery of the plated layer, providing a solder on the board main surface in a vicinity of an electronic element, and providing the electronic element on the board main surface and attaching the electronic element to an interposer board.

